

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT7566199

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	JUSTIN SCOTT KAYSER	08/16/2020
RECEIVING PARTY DATA		
Name:	GLOBALWAFERS CO., LTD.	
Street Address:	NO. 8 INDUSTRIAL EAST ROAD 2	
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK	
City:	HSINCHU	
State/Country:	TAIWAN	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	17956402
CORRESPONDENCE DATA		
Fax Number:	(314)621-5065	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
Phone:	3146215070	
Email:	uspatents@atllp.com	
Correspondent Name:	ARMSTRONG TEASDALE LLP	
Address Line 1:	7700 FORSYTH BLVD., SUITE 1800	
Address Line 4:	ST. LOUIS, MISSOURI 63105	
ATTORNEY DOCKET NUMBER:	28744-5629 171025.9	
NAME OF SUBMITTER:	MICHAEL J. VANDER MOLEN	
SIGNATURE:	/Michael J. Vander Molen/	
DATE SIGNED:	09/29/2022	
Total Attachments: 3		
source=171025.1 Parent Assignment-37631967#page1.tif		
source=171025.1 Parent Assignment-37631967#page2.tif		
source=171025.1 Parent Assignment-37631967#page3.tif		

ASSIGNMENT

WHEREAS, I Justin Scott Kayser of Wentzville, Missouri, have invented an improvement in CLEAVE SYSTEMS HAVING SPRING MEMBERS FOR CLEAVING A SEMICONDUCTOR STRUCTURE AND METHODS FOR CLEAVING SUCH STRUCTURES and have executed an application for a United States patent based thereon filed September 27, 2019, assigned Serial No. 62/906,860;

AND, WHEREAS, GlobalWafers Co., Ltd., a company organized and existing under the laws of Taiwan and having its registered address at No. 8. Industrial East Road 2, Science-Based Industrial Park, Hsinchu, Taiwan R.O.C. (hereinafter referred to as "ASSIGNEE") is desirous of acquiring certain rights thereunder;

NOW, THEREFORE, for one dollar and other good and valuable consideration, receipt of all of which is hereby acknowledged, we have agreed to and do hereby sell, assign and transfer unto said ASSIGNEE the entire right, title and interest in and throughout the United States of America (including its territories and dependencies) and all countries foreign thereto in and to said invention, said United States application, any other United States applications (including provisional, non-provisional, divisional, continuing, or reissue applications) based in whole or in part on said United States application or in whole or in part on said invention, any foreign applications based in whole or in part on any of the aforesaid United States applications or in whole or in part on said invention, and any and all patents (including extensions thereof) of any country which have been or may be granted on any of the aforesaid applications or on said invention or any part thereof;

TO BE HELD AND ENJOYED by said ASSIGNEE, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by us had no sale and assignment of said interest been made;

AND We hereby authorize and request the Commissioner of Patents of the United States of America to issue any and all United States patents which may be granted upon said United States applications or any of them, or upon said invention or any part thereof, to said ASSIGNEE;

AND We hereby jointly and severally agree for ourselves and for our respective heirs, executors and administrators, to execute without further consideration any further lawful documents and any further assurances, and any provisional, non-provisional, divisional, continuing, reissue, or other applications for patents of any country, that may be deemed necessary by said ASSIGNEE fully to secure to said ASSIGNEE its interest as aforesaid in and to said invention or any part thereof, and in and to said several patents or any of them;

AND We hereby jointly and severally covenant for ourselves and our respective legal representatives that we have granted no right or license to make, use or sell said invention, to anyone except said ASSIGNEE, that prior to the execution of this deed our right, title and interest in said

invention had not been otherwise encumbered, and that we have not executed and will not execute any instrument in conflict herewith.

IN WITNESS WHEREOF, I have hereunto set my hand.

Signature: Justin Scott Kayser Date: _____

STATE OF _____
COUNTY OF _____

On this _____ day of _____, 20____ before me, a Notary Public, personally appeared _____, to me known to be the person described in and who executed the foregoing assignment and acknowledged that he executed same as his free act and deed.

IN TESTIMONY WHEREOF, I have hereunto set my hand and seal the date and year last above written.

(Notary Public)

SECTION BELOW IS FOR USE ONLY IF NOT SIGNING IN FRONT OF A NOTARY

Signature: Justin Scott Kayser Date: 8-16-20

Witnessed by: Sara Kayson 8-16-20
Signature Printed Name of Witness

Witnessed by: Justin Scott Kayser 8-16-20
Signature Printed Name of Witness

For and on behalf of GlobalWafers Company, Ltd.

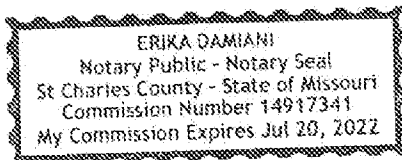
Paul Markowitz
 Paul Markowitz
 Director of Intellectual Property

Feb. 11, 2020
 Date

STATE OF *Missouri*)
 COUNTY OF *St. Charles*)

On this *11* day of *February*, 20 *20* before me, a Notary Public, personally appeared *Paul Markowitz*, to me known to be the person described in and who executed the foregoing assignment and acknowledged that he executed same as his free act and deed.

IN TESTIMONY WHEREOF, I have hereunto set my hand and seal the date and year last above written.



Erika Damiani
 (Notary Public)